



Click [here](#) for the 3D model.

Dimensions

| | |
|---|-----------------|
| L | 1.6mm +/-0.2mm |
| W | 3.2mm +/-0.2mm |
| T | 0.8mm +/-0.10mm |

Packaging Specifications

| | |
|--------------------|------------------------|
| Packaging | T&R, 180mm, Paper Tape |
| Packaging Quantity | 4000 |

General Information

| | |
|-------------|--|
| Series | Array Comm COG Flex |
| Style | SMD Array |
| Description | SMD, MLCC, Array, Flex Termination, Class II |
| RoHS | Yes |
| Termination | Flexible Termination |
| AEC-Q200 | No |
| Chip Size | 0612 |
| MSL | 1 |

Specifications

| | |
|-------------------------|--------------------|
| Capacitance | 390 pF |
| Capacitance Tolerance | 10% |
| Voltage DC | 25 VDC |
| Temperature Range | -55/+125°C |
| Temperature Coefficient | COG |
| Dissipation Factor | 0.1% 1 MHz 1.0Vrms |
| Insulation Resistance | 100 GOhms |